



## Materials Declaration Form


<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2017-06-07</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section		<b>Contact Email *</b> Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>LAURENT TOSI</b>	<b>Representative Title</b>	<b>MDG MD CHAMPION</b>
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	laurent.tosi@st.com
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement			
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Legal Statement			
<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C32-FDW6TP/C	PT6P*24321TA	A	3068	2017-06-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	34	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
TSSOP	NAC	8	L bend	
Comment	TSSOP 8 BODY 4.4 PITCH 0.65			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
5 - Product(s) is obsolete, no information is available	FALSE
6 - Product(s) is unknown, no information is available	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	PT6P*24321TA				5000000.0	1000001.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.320	mg	supplier	die	Silicon (Si)	7440-21-3		0.308	mg	962500	9059
				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	3125	29
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	3125	29
				supplier	Passivation	Silicon Oxide	7631-86-9		0.010	mg	31250	294
Lead-frame	M-011 Other inorganic materials	14.579	mg	supplier	alloy	Copper (Cu)	7440-50-8		14.147	mg	970339	416079
				supplier	alloy	Iron (Fe)	7439-89-6		0.341	mg	23360	10017
				supplier	alloy	Zinc (Zn)	7440-66-6		0.017	mg	1195	512
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	836	359
				supplier	coating	Nickel (Ni)	7440-02-0		0.057	mg	3906	1675
				supplier	coating	Palladium (Pd)	7440-05-3		0.002	mg	127	54
				supplier	coating	Gold (Au)	7440-57-5		0.002	mg	118	51
				supplier	coating	Silver (Ag)	7440-22-4		0.002	mg	118	51
Die Attach	M-011 Other inorganic materials	0.049	mg	supplier	glue or soft solder	Poly(tetrafluoroethylene)	9002-84-0		0.020	mg	400000	576
				supplier	glue or soft solder	silica	60676-86-0		0.009	mg	190000	274
				supplier	glue or soft solder	Bismaleimide resin	105391-33-1		0.010	mg	210000	303
				supplier	glue or soft solder	Trimethylolpropane trimethacrylate	3290-92-4		0.005	mg	100000	144
				supplier	glue or soft solder	[(vinyl)oxy)methyl]cyclohexane	17351-75-6		0.002	mg	50000	72
Wires	M-011 Other inorganic materials	0.019	mg	supplier	glue or soft solder	Hexanediol diacrylate	13048-33-4		0.002	mg	50000	72
				supplier	Bonding wire	Copper (Cu)	7440-50-8		0.019	mg	1000000	546
Encapsulation	M-011 Other inorganic materials	19.033	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		16.578	mg	871007	487594
				supplier	Moulding Compound	Epoxy Resin	85954-11-6		1.523	mg	79996	44782
				supplier	Moulding Compound	Phenol Resin	26834-02-6		0.761	mg	39998	22391
				supplier	Moulding Compound	Carbon black	1333-86-4		0.095	mg	5000	2799
				supplier	Moulding Compound	Bismuth compound	7440-69-9		0.076	mg	4000	2239